

Maximum Ratings

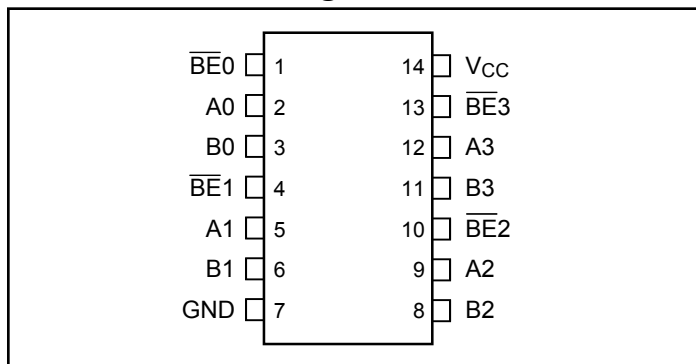
(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power Applied	-40°C to +85°C
Supply Voltage to Ground Potential.....	-0.5V to +4.6V
DC Input Voltage	-0.5V to +4.6V
DC Output Current.....	120mA
Power Dissipation	0.5W

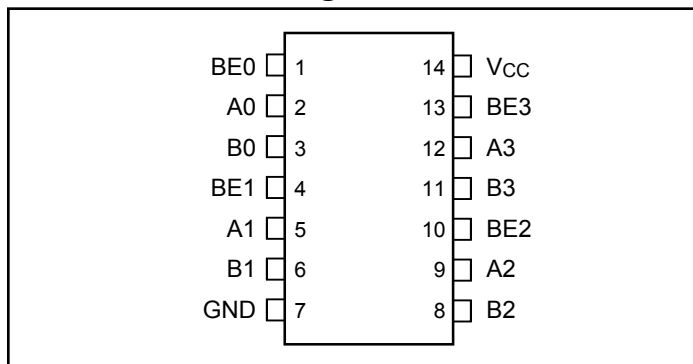
Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

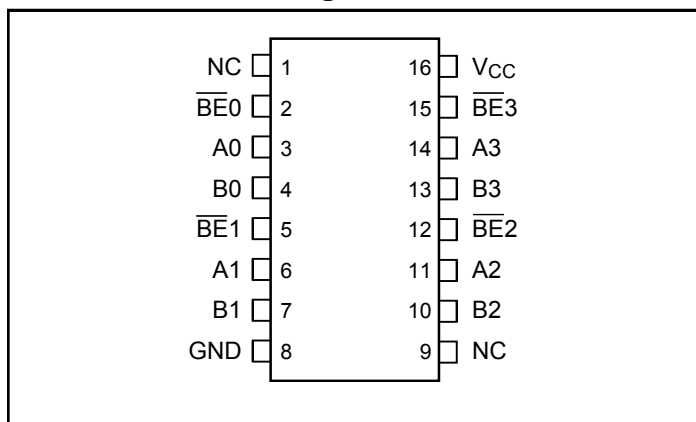
PI3B3125 14-Pin Configuration



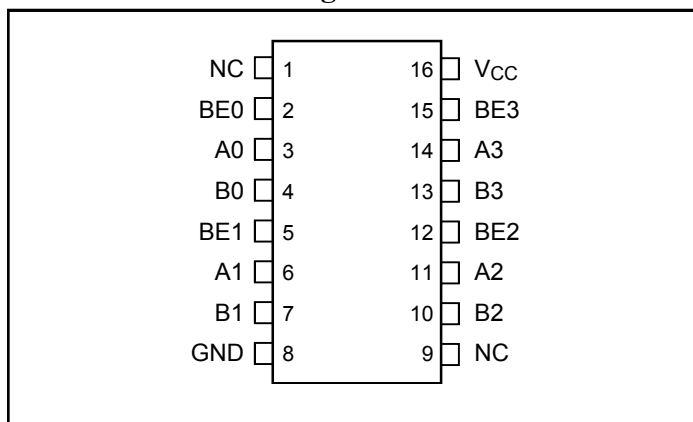
PI3B3126 14-Pin Configuration



PI3B3125 16-Pin Configuration



PI3B3126 16-Pin Configuration



Pin Description

Pin Name	Description
$\overline{BE}_N$	Switch Enable (PI3B3125)
BE_N	Switch Enable (PI3B3126)
A_3 - A_0	Bus A
B_3 - B_0	Bus B
V_{CC}	Power
GND	Ground

Truth Table⁽¹⁾

PI3B3125 $\overline{BE}_N$	PI3B3126 BE_N	A_N	B_N	V_{CC}	Function
$X^{(2)}$	X	Hi-Z	Hi-Z	GND	Disconnect
H	L	Hi-Z	Hi-Z	V_{CC}	Disconnect
L	H	Bn	An	V_{CC}	Connect

Notes:

- H = High Voltage Level, L = Low Voltage Level, Hi-Z = High Impedance, X = Don't Care
- A pull-up resistor should be provided for power-up protection.

DC Electrical Characteristics (Over the Operating Range, $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{CC} = 3.3\text{V} \pm 10\%$)

Parameters	Description	Test Conditions ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units
V_{IH}	Input HIGH Voltage	Guaranteed Logic HIGH Level	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Logic LOW Level	-0.5		0.8	
I_{IH}	Input HIGH Current	$V_{CC} = \text{Max.}, V_{IN} = V_{CC}$			± 1	μA
I_{IL}	Input LOW Current	$V_{CC} = \text{Max.}, V_{IN} = \text{GND}$			± 1	
I_{OFF}	Off Current	$V_{CC} = 0, V_{OUT} = 3 \text{ to } 3.6\text{V}$			10	
V_{IK}	Clamp Diode Voltage	$V_{CC} = \text{Min.}, I_{IN} = -18\text{mA}$			-1.2	V
R_{ON}	Switch On-Resistance ⁽³⁾	$V_{CC} = \text{Min.}, V_{IN} = 0.0\text{V}, I_{ON} = 48\text{mA or } 60\text{mA}$		5	8	Ω
		$V_{CC} = \text{Min.}, V_{IN} = 2.4\text{V}, I_{ON} = 15\text{mA}$		10	17	

Capacitance ($T_A = 25^{\circ}\text{C}$, $f = 1 \text{ MHz}$)

Parameters ⁽⁴⁾	Description	Test Conditions	Typ.	Units
C_{IN}	Input Capacitance	$V_{IN} = 0\text{V}$	3.5	pF
C_{OFF}	A/B Capacitance, Switch Off		8	

Notes:

- For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at $V_{CC} = 3.3\text{V}$, $T_A = 25^{\circ}\text{C}$ ambient and maximum loading.
- Measured by the voltage drop between A and B pin at indicated current through the switch. On-Resistance is determined by the lower of the voltages on the two (A, B) pins.
- This parameter is determined by device characterization but is not production tested.

Power Supply Characteristics

Parameters	Description	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Units
I_{CC}	Quiescent Power Supply Current	$V_{CC} = \text{Max.}$	$V_{IN} = \text{GND or } V_{CC}$		0.1	3	μA
ΔI_{CC}	Supply Current per Input HIGH	$V_{CC} = \text{Max.}$	$V_{IN} = 3.0\text{V}^{(3)}$			750	

Notes:

- For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device.
- Typical values are at $V_{CC} = 3.3\text{V}$, $+25^{\circ}\text{C}$ ambient.
- Per driven input (control inputs only); A and B pins do not contribute to I_{CC} .

PI3B3125 Switching Characteristics over Operating Range

Parameters	Description	Conditions ⁽¹⁾	PI3B3125		Units
			Com.		
			Min.	Max.	
t _{PLH} t _{PHL}	Propagation Delay ^(2,3) Ax to Bx, Bx to Ax	C _L = 50pF R _L = 500Ω		0.25	ns
t _{PZH} t _{PZL}	Bus Enable Time	C _L = 50pF, R _L = 500Ω,	1.0	3.0	
t _{PHZ} t _{PLZ}	Bus Disable Time	R _L = 500Ω	1.0	4.0	

PI3B3126 Switching Characteristics over Operating Range

Parameters	Description	Conditions ⁽¹⁾	PI3B3126		Units
			Com.		
			Min.	Max.	
t _{PLH} t _{PHL}	Propagation Delay ^(2,3) Ax to Bx, Bx to Ax	C _L = 50pF R _L = 500Ω		0.25	ns
t _{PZH} t _{PZL}	Bus Enable Time	C _L = 50pF, R _L = 500Ω,	1.0	2.5	
t _{PHZ} t _{PLZ}	Bus Disable Time	R _L = 500Ω	1.0	4.0	

Notes:

1. See test circuit and waveforms.
2. This parameter is guaranteed but not tested on Propagation Delays.
3. The bus switch contributes no propagational delay other than the RC delay of the On-Resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25ns for 50pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interaction with the load on the driven side.

Applications Information
Logic Inputs

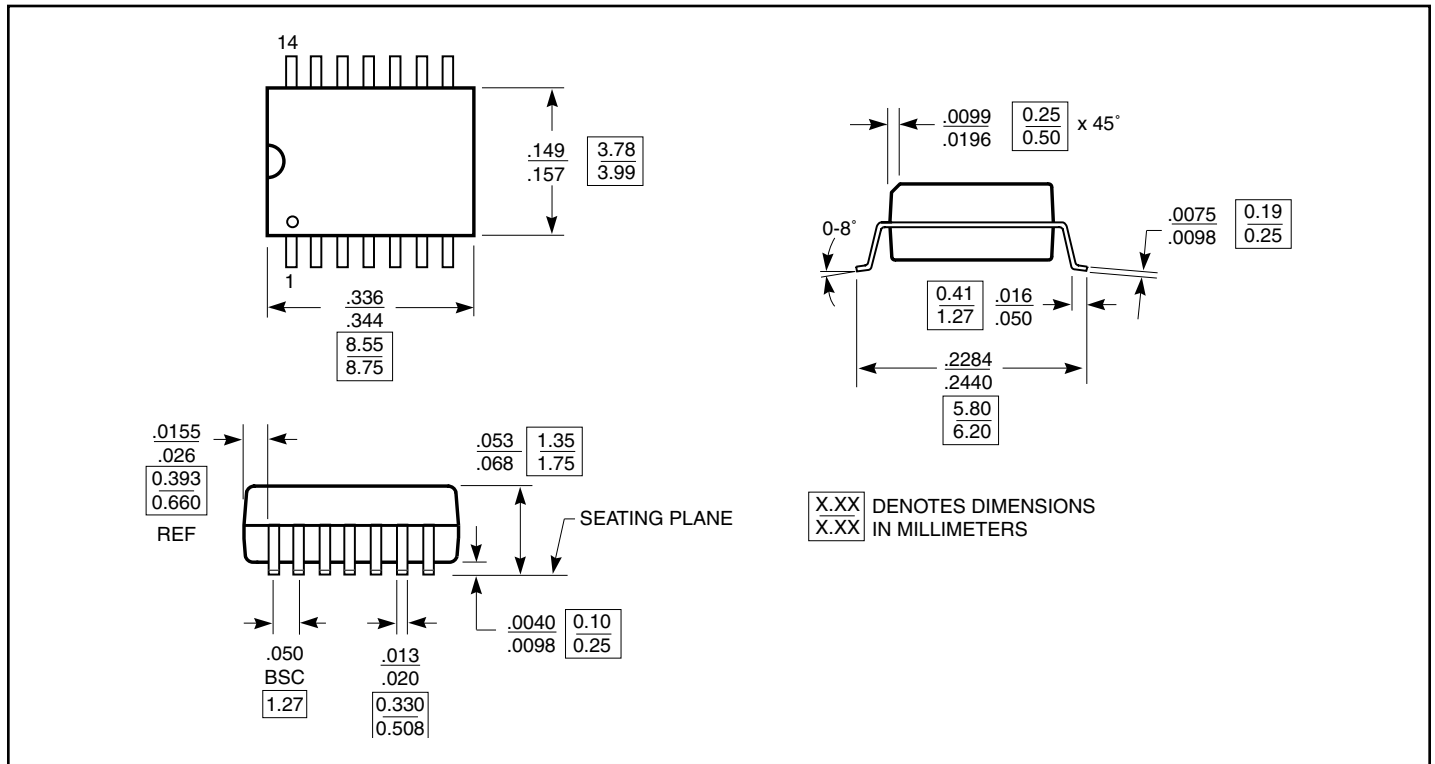
The logic control inputs can be driven up to +3.6V regardless of the supply voltage. For example, given a + 3.3V supply, IN may be driven low to 0V and high to 3.6V. Driving IN Rail-to-Rail® minimizes power consumption.

Power-Supply Sequencing and Hot-Plug Information

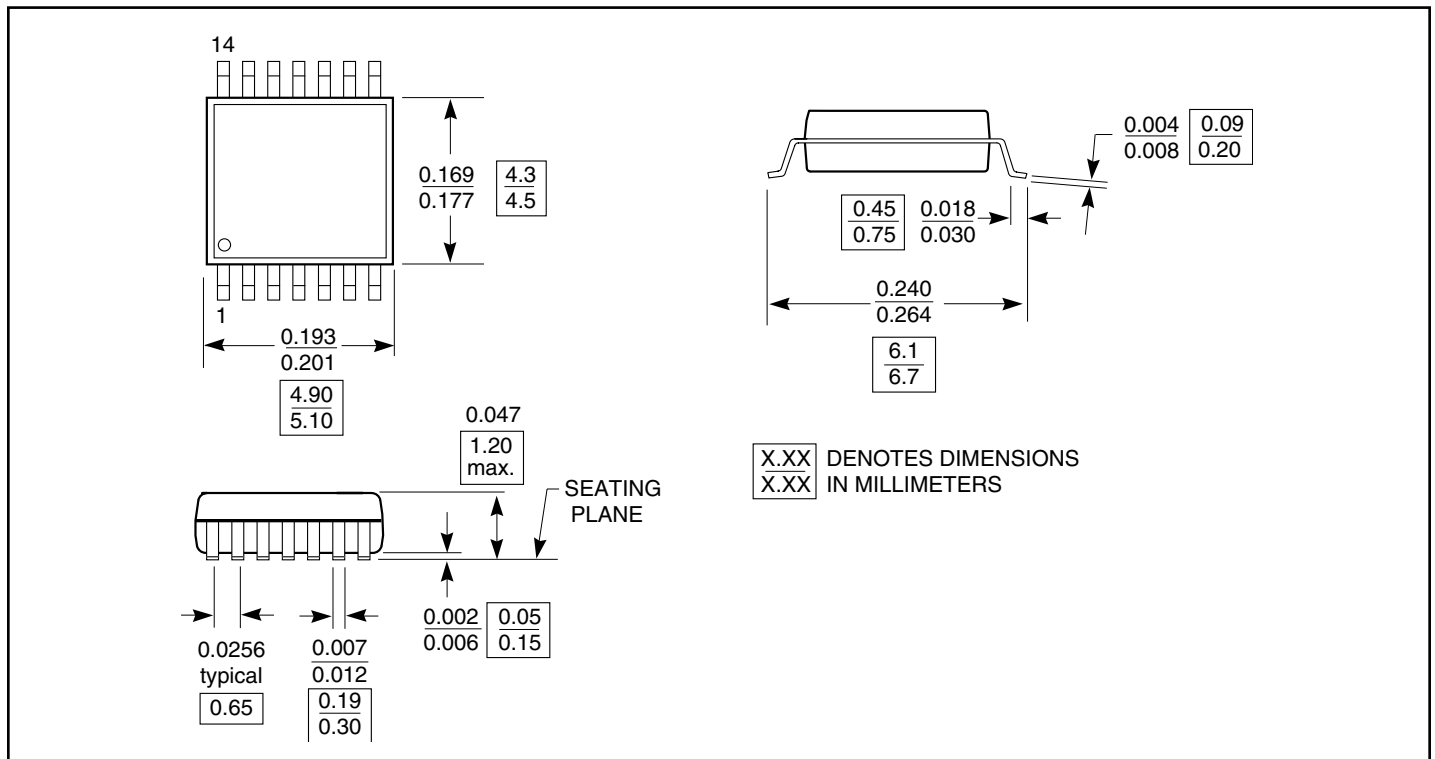
Proper power-supply sequencing is recommended for all CMOS devices. Always apply V_{CC} and GND before applying signals to input/output or control pins.

Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.

Packaging Mechanical: 14-pin SOIC (W)



Packaging Mechanical: 14-pin TSSOP (L)



Technical drawings of a 16-pin DIP package showing top, side, and detail views with dimensions in inches and millimeters.

Top View: Shows a rectangular package with 16 pins. Dimensions include a width of .189 (4.80) and .197 (5.00), and a height of .150 (3.81) and .157 (3.99). Pin pitch is .025 (0.635) BSC. Pin width is .008 (0.203) REF. Pin height is .053 (1.35) and .069 (1.75). Pin thickness is .004 (0.101) and .010 (0.254). Pin spacing is .008 (0.203) and .012 (0.305).

Side View: Shows the package profile with a maximum height of .010 (0.254) and a minimum height of .008 (0.203). The package is seated on a seating plane. The pin height is .016 (0.41) and .035 (0.89). The pin thickness is .041 (1.04) REF. The pin spacing is .015 x 45° (0.38). The pin height is .007 (0.178) and .010 (0.254). The pin thickness is .041 (1.27) and .016 (0.050). The pin spacing is .228 (5.79) and .244 (6.19).

Detail A: Shows a cross-section of the package with dimensions .008 (0.20) MIN., .008 (0.20) MAX., .013 (0.33), .016 (0.41), .035 (0.89), .041 (1.04) REF, .015 x 45° (0.38), .007 (0.178), .010 (0.254), .041 (1.27), .016 (0.050), .228 (5.79), .244 (6.19).

Legend: X.XX DENOTES DIMENSIONS IN MILLIMETERS

Ordering Code	Package Code	Package Description
PI3B3125L	L	14-Pin TSSOP
PI3B3125LE	L	Pb-free & Green, 14-Pin TSSOP
PI3B3125W	W	14-pin SOIC
PI3B3125WE	W	Pb-free & Green, 14-pin SOIC
PI3B3125Q	Q	16-pin QSOP
PI3B3125QE	Q	Pb-free & Green, 16-pin QSOP
PI3B3126L	L	14-Pin TSSOP
PI3B3126LE	L	Pb-free & Green, 14-Pin TSSOP
PI3B3126W	W	14-pin SOIC
PI3B3126WE	W	Pb-free & Green, 14-pin SOIC
PI3B3126Q	Q	16-pin QSOP
PI3B3126QE	Q	Pb-free & Green, 16-pin QSOP

1. Thermal Characteristics can be found on the web at www.pericom.com/packaging/